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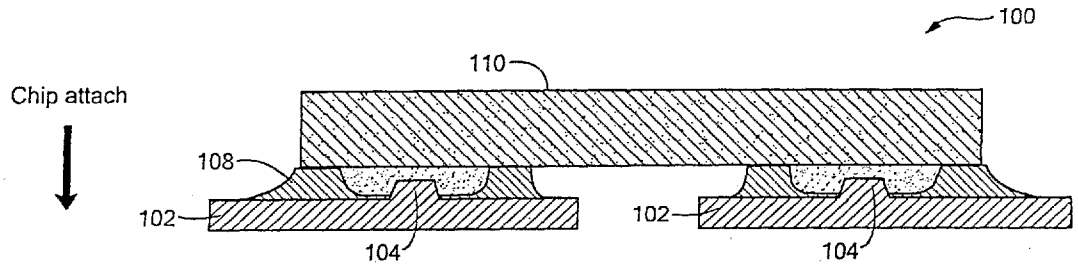
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(54) Title: METHODS AND APPARATUS FOR FLIP-CHIP-ON-LEAD SEMICONDUCTOR PACKAGE



(57) Abstract: Fabrication of a semiconductor package includes placing a conductive material (106) on a protrusion (104) from a leadframe (102) to form a first assembly, forming a non- conductive mask (109) about the protrusion, and placing a die (110) on the first assembly, the die having an active area. Fabrication can further include reflowing the conductive material to form a second assembly such that a connection extends from the die active area, through the conductive material (106) , to the protrusion (104) . A semiconductor package (100) includes a leadframe (102) having a protrusion (104) , a conductive material (106) reflowed to the protrusion (104) , and a die (110) having an active area coupled to the protrusion (104) by the reflowed solder (106) .

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